

In the Claims:

Please enter the following amended claims 1, 17, and 44:

1. (Once Amended) A structure comprising:

    a substrate having a top surface for receiving a die;

    a printed circuit board attached to a bottom surface of said substrate;

    a support pad attached to said top surface of said substrate, said support pad being situated underneath said die, said support pad being coupled to said die by a down bonding wire;

    at least one via in said substrate;

    said at least one via providing an electrical connection between a signal bond pad of said die and said printed circuit board.

17. (Once Amended) A structure comprising:

    a substrate having a top surface and a bottom surface;

    a semiconductor die attached to said top surface of said substrate;

    a heat spreader attached to said bottom surface of said substrate;

    a support pad attached to said top surface of said substrate, said support pad being connected to said heat spreader;

    a first via in said substrate;

said first via providing a connection between said semiconductor die and said heat

Cont'd

spreader.

C2

44. (Once Amended) A structure comprising:

a substrate having a top surface and a bottom surface;

a semiconductor die attached to said top surface of said substrate;

a heat spreader attached to said bottom surface of said substrate;

C3

a support pad attached to said top surface of said substrate, said support pad being connected to said heat spreader;

a first plurality of vias in said substrate;

said first plurality of vias providing a connection between said semiconductor die and said heat spreader.